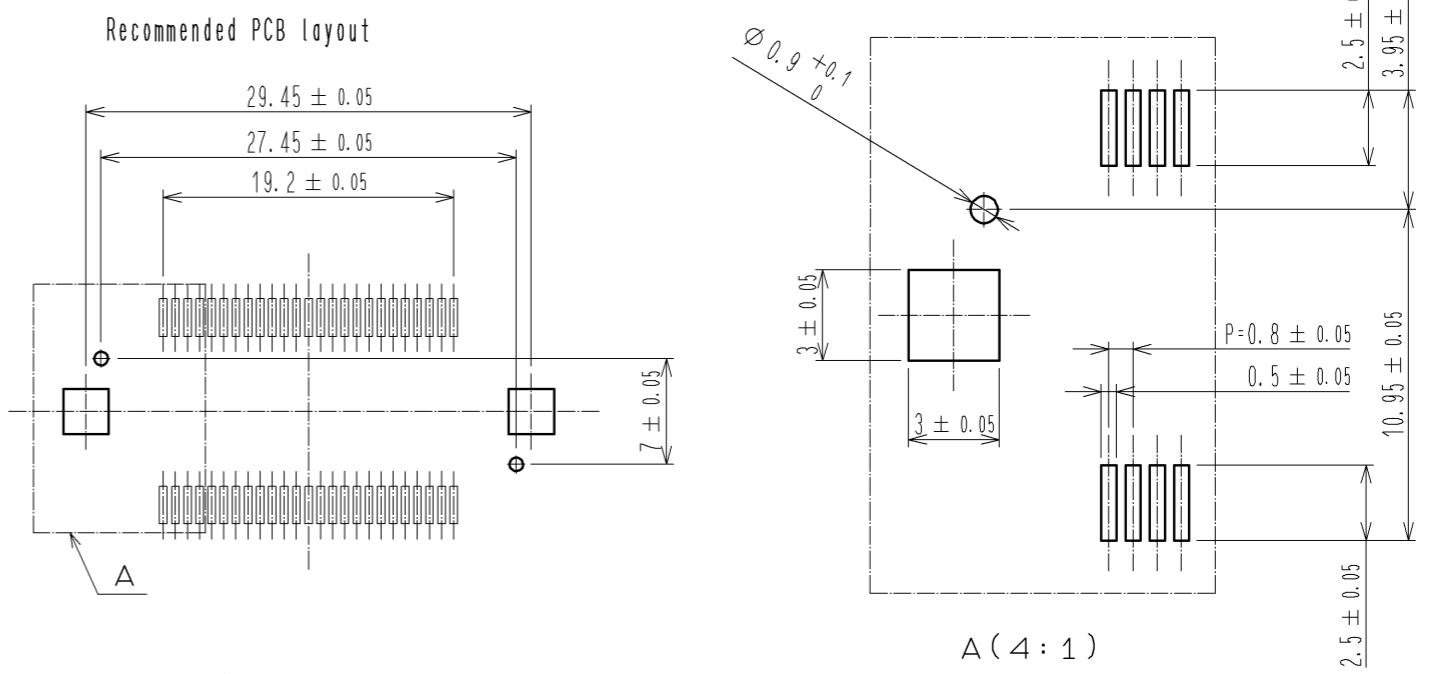
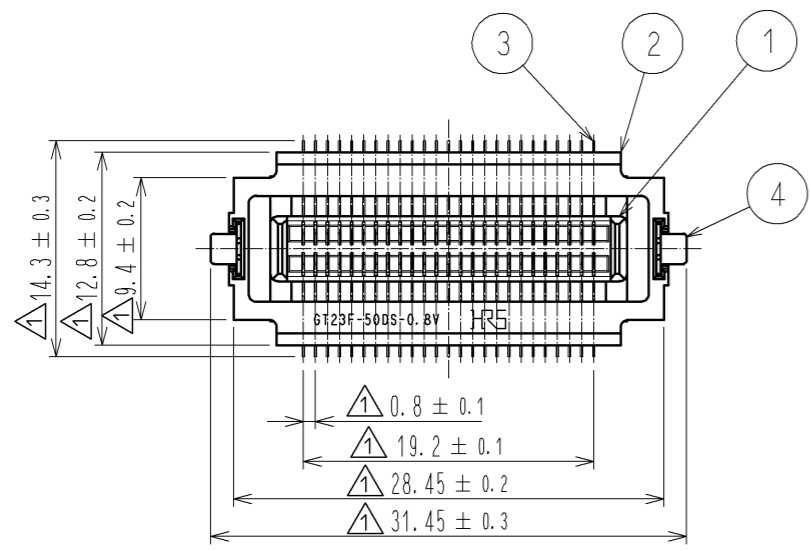
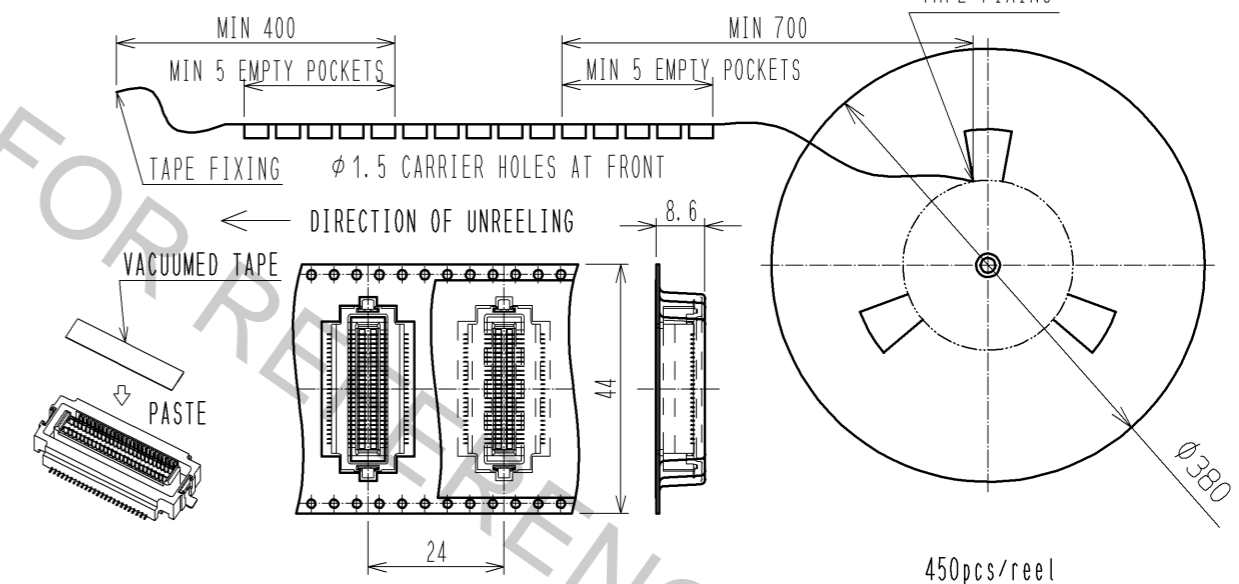


ELV, RoHS COMPLIANT

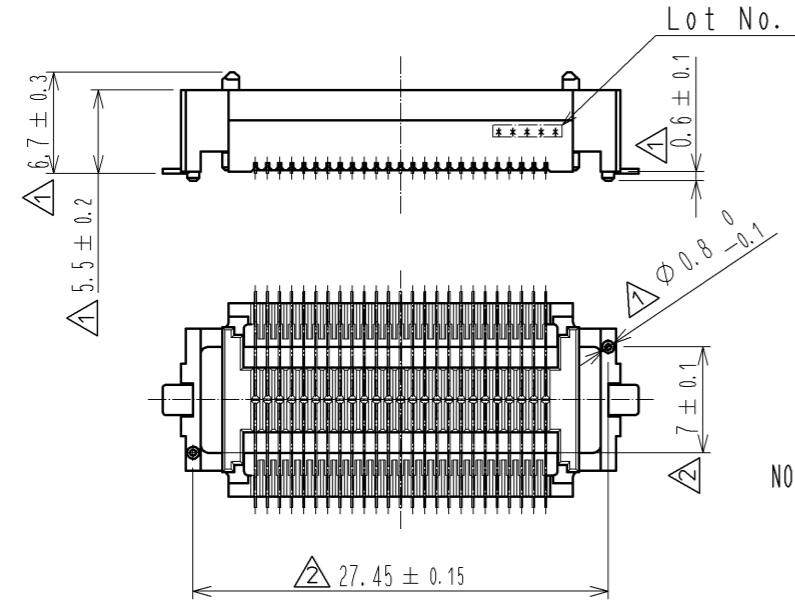
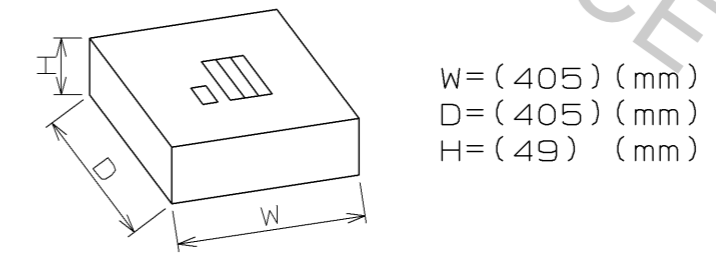


PACKING STYLE

1. Place connectors into an embossed carrier tape.



2. Put a reel into a cardboard.

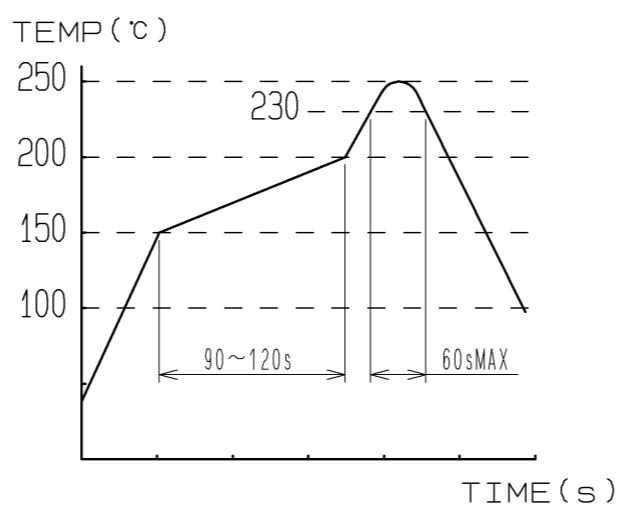


NOTE 1. CO-PLANARITY SHALL BE 0.1 MAX.
2. RECOMMENDED SOLDER THICKNESS=0.15

RECOMMENDED TEMPERATURE PROFILE FOR REFLOW

- 1. PEAK : 250°C
- 2. OVER230°C : 60sec MAX
- 3. PREHEAT : 150~200°C, 90~120sec
- 4. NO. OF CYCLES : 2 TIMES MAX

*This temperature profile is the recommended value. The temperature profile may differ depending on the cream solder, the manufacturer, the PC Board size, and other mounting materials, etc. Please confirm the mounting condition before applying the recommended temperature profile.



2	PA	BLACK	4	BRASS	TIN PLATING						
1	PA	BLACK	3	PHOSPHOR BRONZE	Contact:GOLD PLATING, Mounting:TIN PLATING						
NO.	MATERIAL	FINISH	REMARKS	NO.	MATERIAL	FINISH	REMARKS				
UNITS	mm	SCALE	2 : 1	COUNT	2	DESCRIPTION OF REVISIONS	DESIGNED	CHECKED	DATE		
				DIS-T-003456		TK. SHISHIKURA		NH. NAKATA		13.08.15	
APPROVED : AR. SHIRAI		10.03.29		DRAWING NO.		EDC3-167666-00					
CHECKED : TY. TAKAHASHI		10.03.29		PART NO.		GT23F-50DS-0.8V					
DESIGNED : TY. SAKASHITA		10.03.29		CODE NO.		CL773-0007-7-00					
DRAWN : KT. MATSUDA		10.03.26									